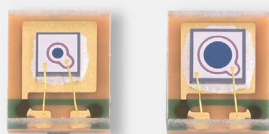


Si APD

S17268 series



Short wavelength type APD, surface mount type package

These are surface mount type short wavelength APDs with enhanced sensitivity in the UV to visible region. They offer high gain, high sensitivity, and low noise in the short wavelength region.

Features

- **Compact, surface mount type package:**
1.8 mm × 2.0 mm × 0.9^t mm
- **High short-wavelength sensitivity:**
QE=82 % ($\lambda=450$ nm)
- **Low bias operation:**
Breakdown voltage=160 V typ.
- **Low noise**
- **High-speed response:**
Cutoff frequency=2 GHz typ.
(S17268-02, $\lambda=450$ nm, M=50)

Applications

- **Optical rangefinders**
- **Flow cytometry**
- **Particle counters**

Structure

Parameter	S17268-02	S17268-05	Unit
Photosensitive area	$\phi 0.2$	$\phi 0.5$	mm
Package	Glass epoxy		-
Seal material	Silicone resin		-

Absolute maximum ratings

Parameter	Symbol	Specification	Unit
Forward current	I_F max	10	mA
Reverse current (DC)	I_R max	200	μ A
Operating temperature*1	T_{opr}	-30 to +100	°C
Storage temperature*1	T_{stg}	-40 to +100	°C
Soldering temperature	T_{sol}	260 (3 times)*2	°C

*1: No dew condensation

When there is a temperature difference between a product and the surrounding area in high humidity environments, dew condensation may occur on the product surface. Dew condensation on the product may cause deterioration in characteristics and reliability.

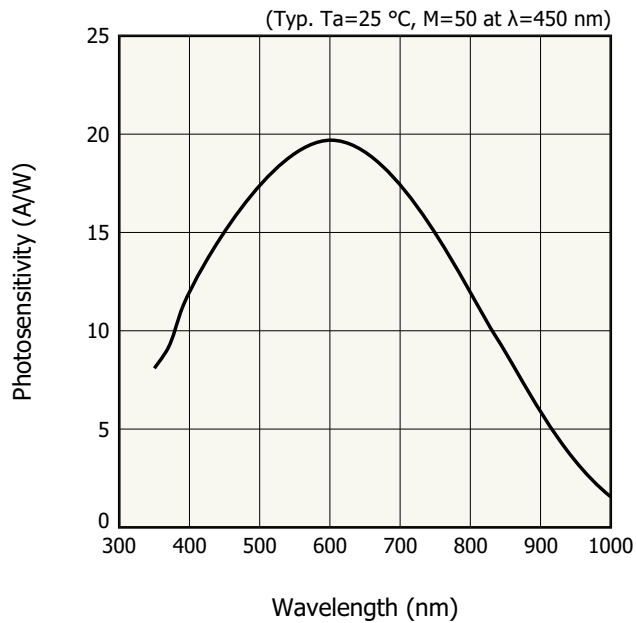
*2: Reflow soldering, JEDEC J-STD-020 MSL 2a, see P.5

Note: Exceeding the absolute maximum ratings even momentarily may cause a drop in product quality. Always be sure to use the product within the absolute maximum ratings.

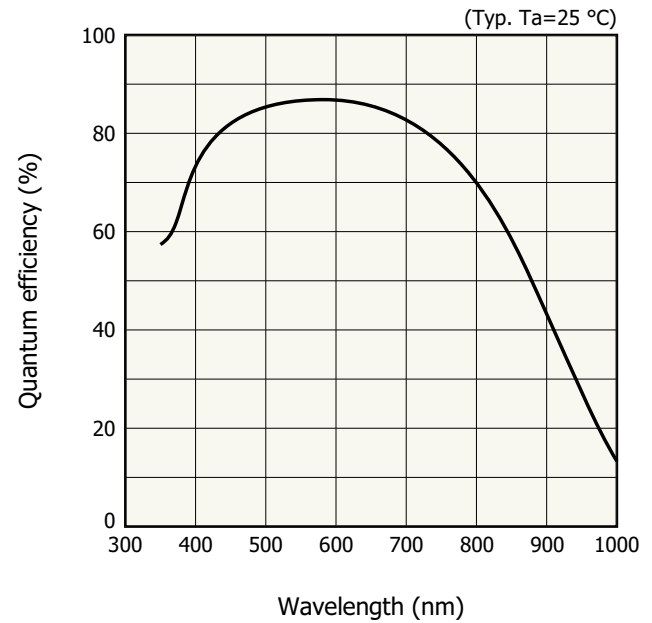
Electrical and optical characteristics (Ta=25 °C, unless otherwise noted)

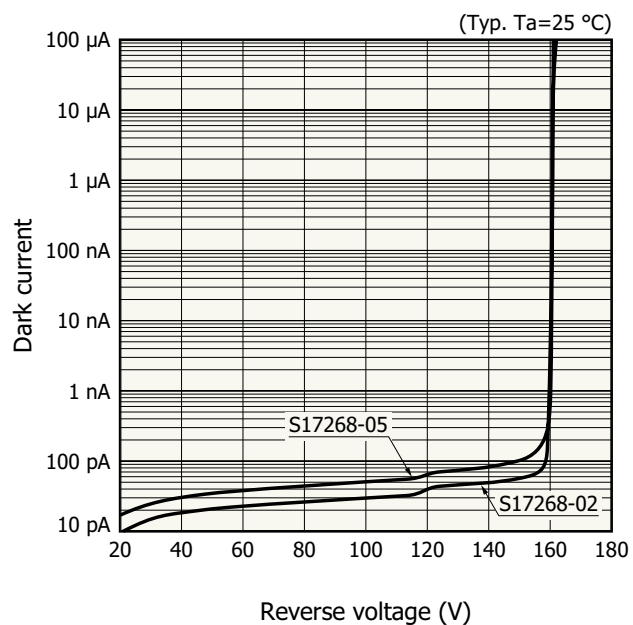
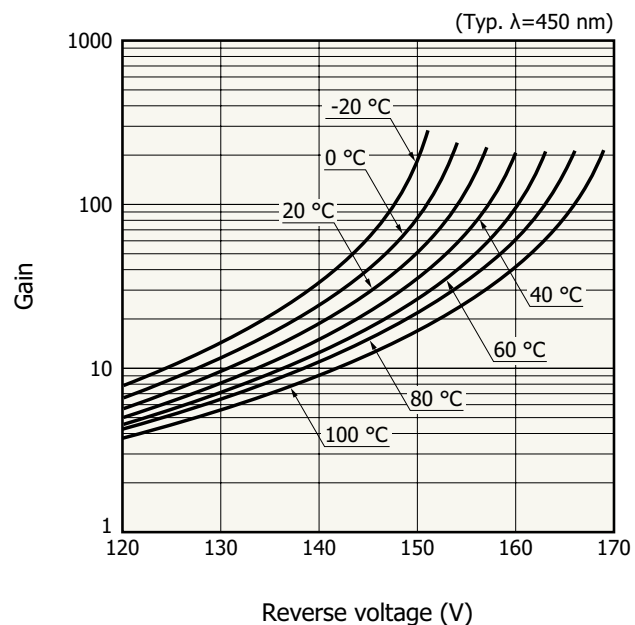
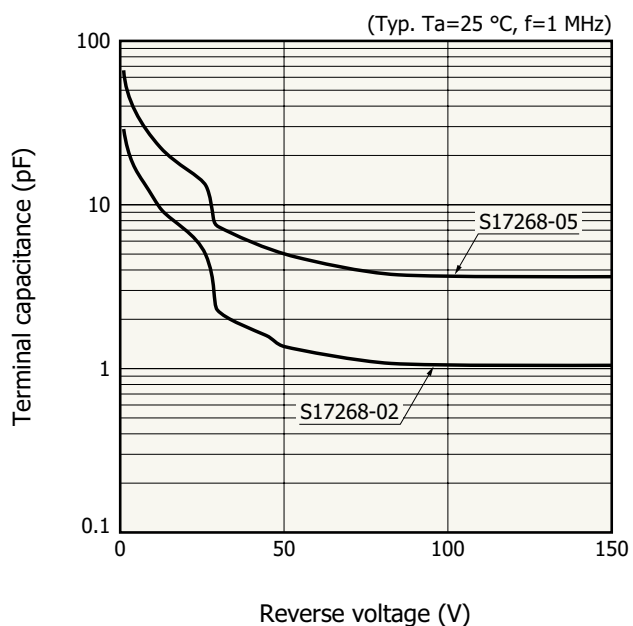
Parameter	Symbol	Condition	S17268-02			S17268-05			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	
Spectral response range	λ	M=1	350 to 1000						nm
Peak sensitivity wavelength	λ_p	M=50	-	600	-	-	600	-	nm
Photosensitivity	S	$\lambda=450$ nm, M=1	-	0.3	-	-	0.3	-	A/W
Quantum efficiency	QE	$\lambda=450$ nm, M=1	-	82	-	-	82	-	%
Breakdown voltage	V _{BR}	I _D =100 μ A	140	160	180	140	160	180	V
Temperature coefficient of breakdown voltage	ΔT_{VBR}		-	0.15	-	-	0.15	-	V/°C
Dark current	I _D	M=50	-	0.1	1	-	0.2	2	nA
Cutoff frequency	f _c	M=50, R _L =50 Ω $\lambda=450$ nm, -3 dB	-	2	-	-	0.8	-	GHz
Terminal capacitance	C _t	M=50, f=1 MHz	-	1.0	-	-	3.6	-	pF
Excess noise factor	F	M=50, $\lambda=450$ nm	-	1.6	-	-	1.6	-	-
Excess noise figure	x	M=50, $\lambda=450$ nm	-	0.12	-	-	0.12	-	-
Gain	M	M=50, $\lambda=450$ nm	-	50	-	-	50	-	-

Spectral response

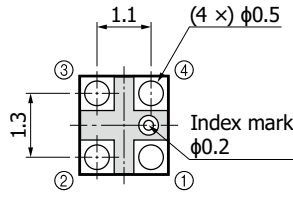
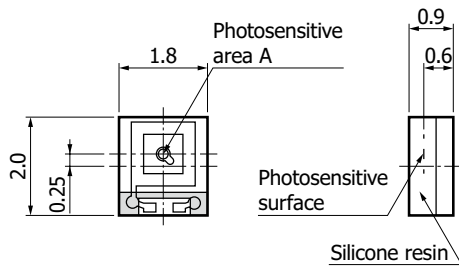


Quantum efficiency vs. wavelength



Dark current vs. reverse voltage**Gain vs. reverse voltage****Terminal capacitance vs. reverse voltage**

Dimensional outline (unit: mm)

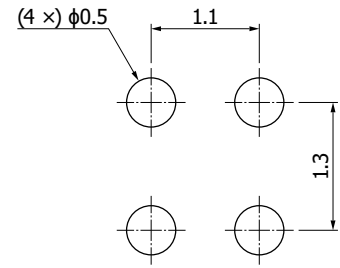


Tolerance unless otherwise noted: ± 0.1
Chip position accuracy with respect to
backside electrode pads: X, Y $\leq \pm 0.15$

- ① Cathode
- ② Anode
- ③ NC
- ④ NC

Type no.	A
S17268-02	$\phi 0.2$
S17268-05	$\phi 0.5$

Recommended land pattern (unit: mm)



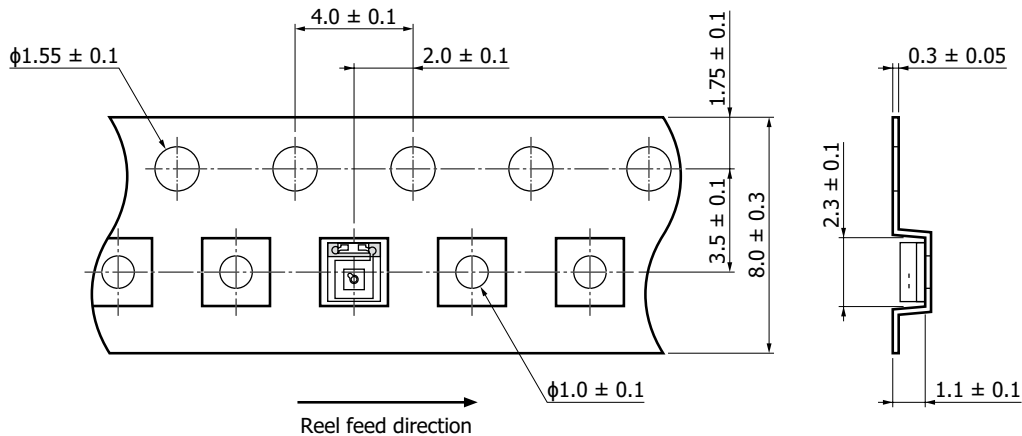
KAPDC0152EA

Standard packing specifications

- Reel (conforms to JEITA ET-7200)

Appearance	Hub diameter	Tape width	Material	Electrostatic characteristics
$\phi 180$ mm	$\phi 60$ mm	8 mm	PS	Conductive

- Embossed tape (unit: mm, material: PS, conductive)



KAPDC0153EA

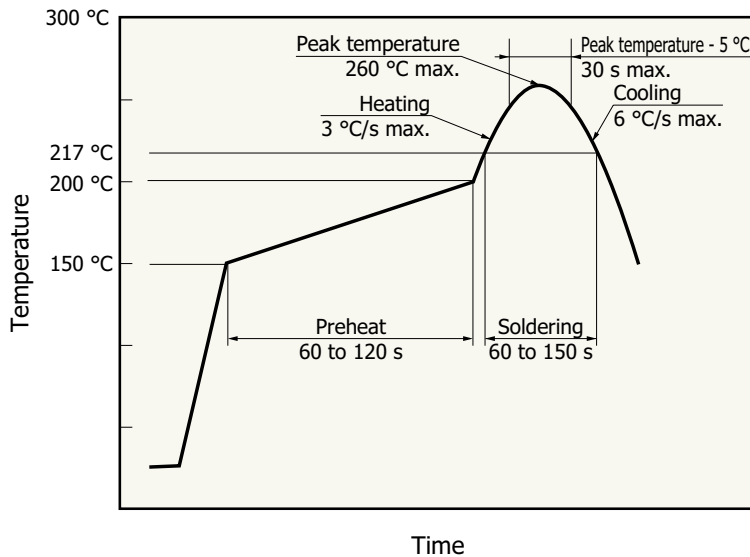
- Packing quantity

1000 pcs/reel

- Packing state

Reel and desiccant in moisture-proof packaging (vacuum-sealed)

Recommended reflow soldering conditions



- After unpacking, store in an environment at a temperature of 30 °C or less and a humidity of 60 % or less, and perform reflow soldering within 4 hours.
- The effect that the product receives during reflow soldering varies depending on the circuit board and reflow oven that are used. When you set reflow soldering conditions, check that problems do not occur in the product by testing out the conditions in advance.

KMPDB0405EC

Baking

If 12 months have passed in an unpacked state or the storage period described above has passed after opening, perform baking before reflow soldering to dehumidify. For the baking method, see the related information "Precautions / Surface mount type products."

Recommended baking conditions

- Temperature: 150 °C, 3 hours, up to twice

Note: When you set baking conditions, check that problems do not occur in the product by testing out the conditions in advance.

Related information

www.hamamatsu.com/sp/ssd/doc_en.html

Precautions

- Disclaimer
- Precautions / Surface mount type products

Catalog

- Technical note / Si APD

The content of this document is current as of August 2025.

Product specifications are subject to change without prior notice due to improvements or other reasons. This document has been carefully prepared and the information contained is believed to be accurate. In rare cases, however, there may be inaccuracies such as text errors. Before using these products, always contact us for the delivery specification sheet to check the latest specifications.

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